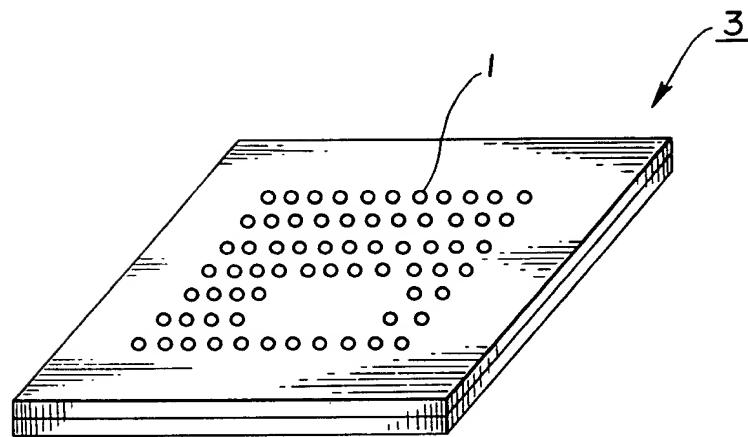


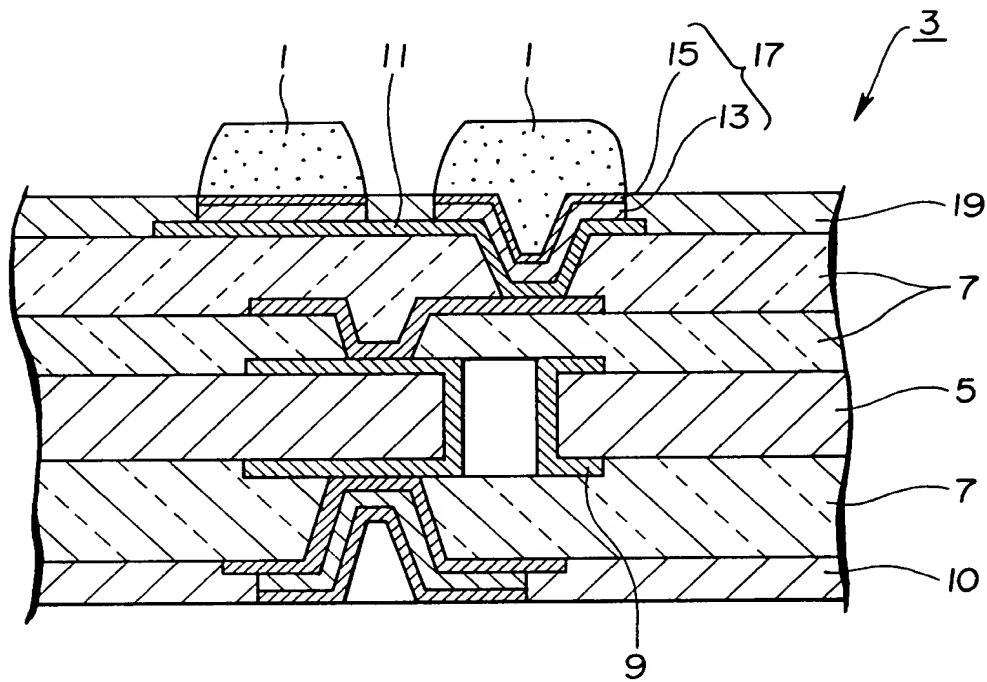


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RELATING TO CIRCUIT BOARD  
HAVING SOLDER BUMPS  
Inventor(s): Haruhiko MURATA et al.  
Appl. No.: 08/825,400

**FIG.1A**

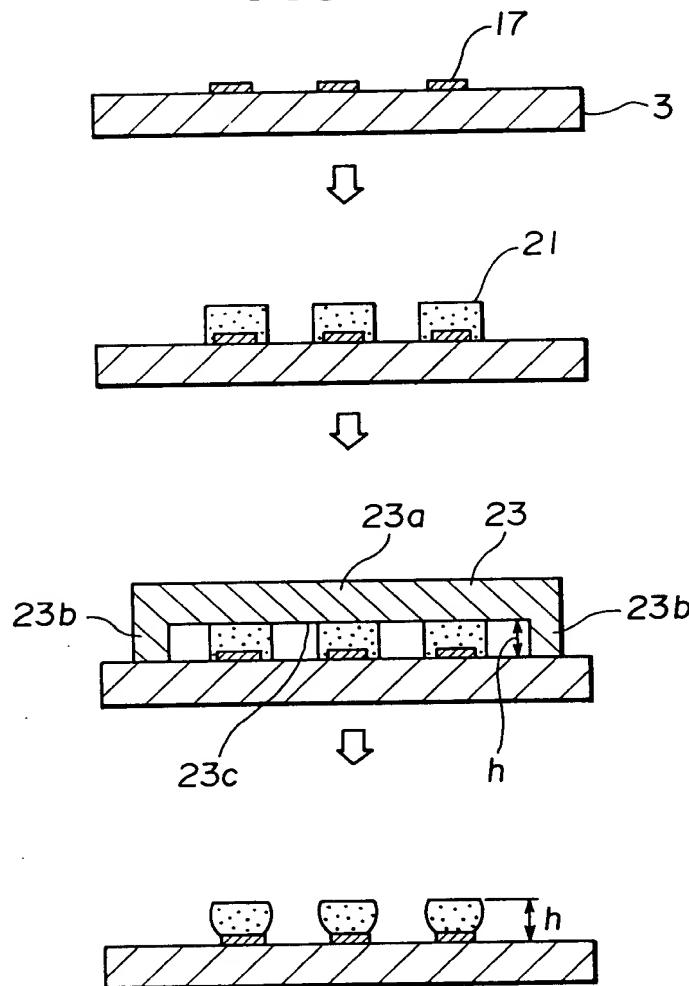


**FIG.1B**

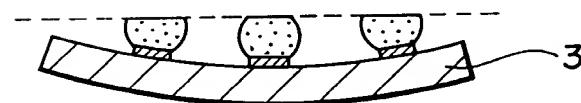




**FIG.2A**

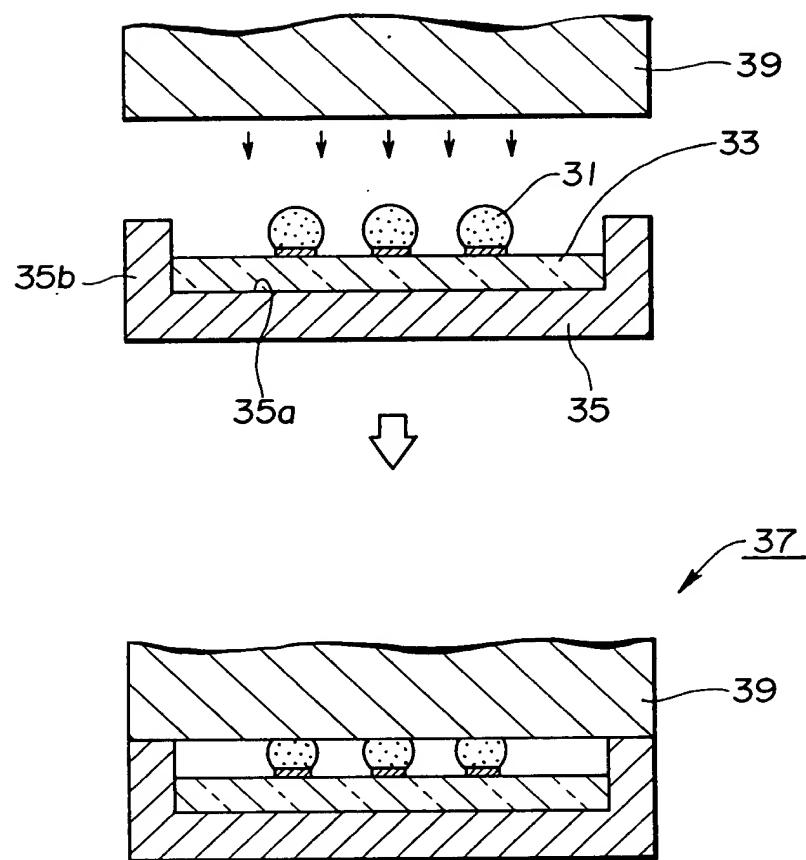


**FIG.2B**



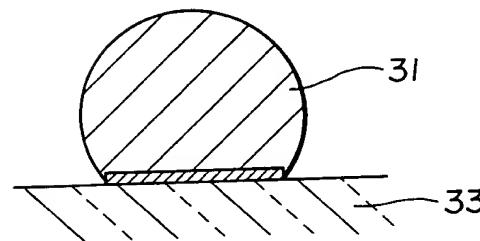


**FIG.3**

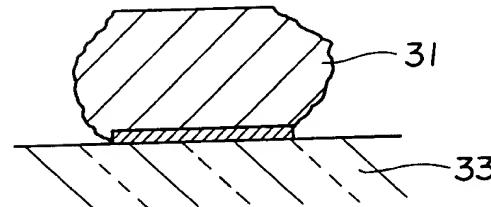


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Appl. No.: 08/825,400

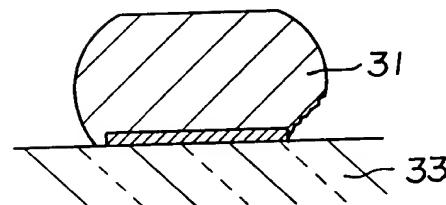
**FIG.4A**



**FIG.4B**



**FIG.4C**



**FIG.5**

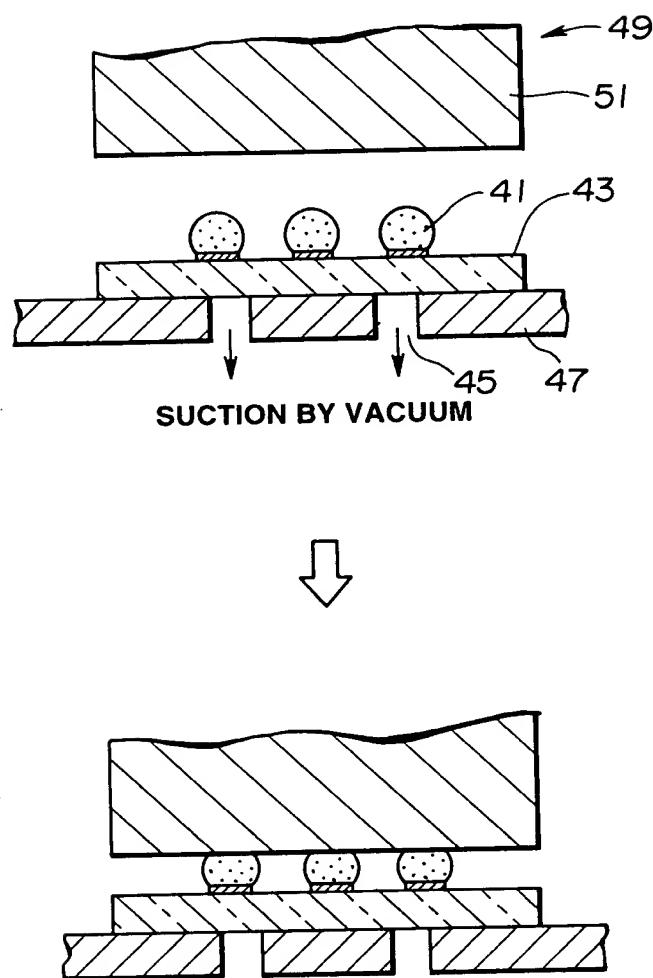


FIG. 6

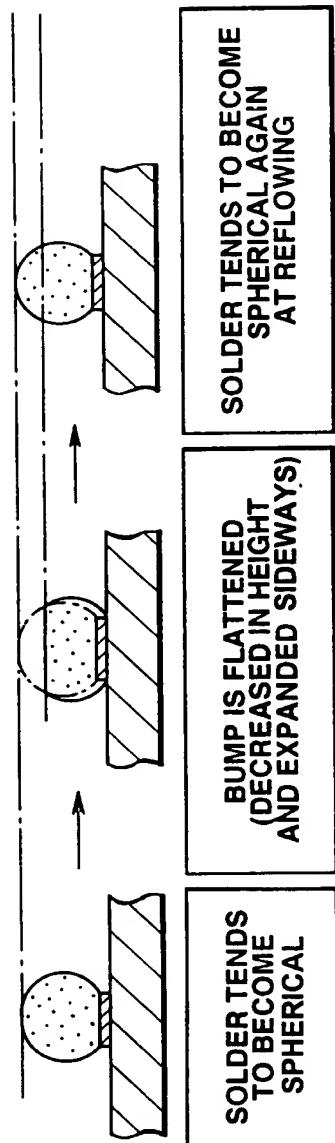


FIG. 7

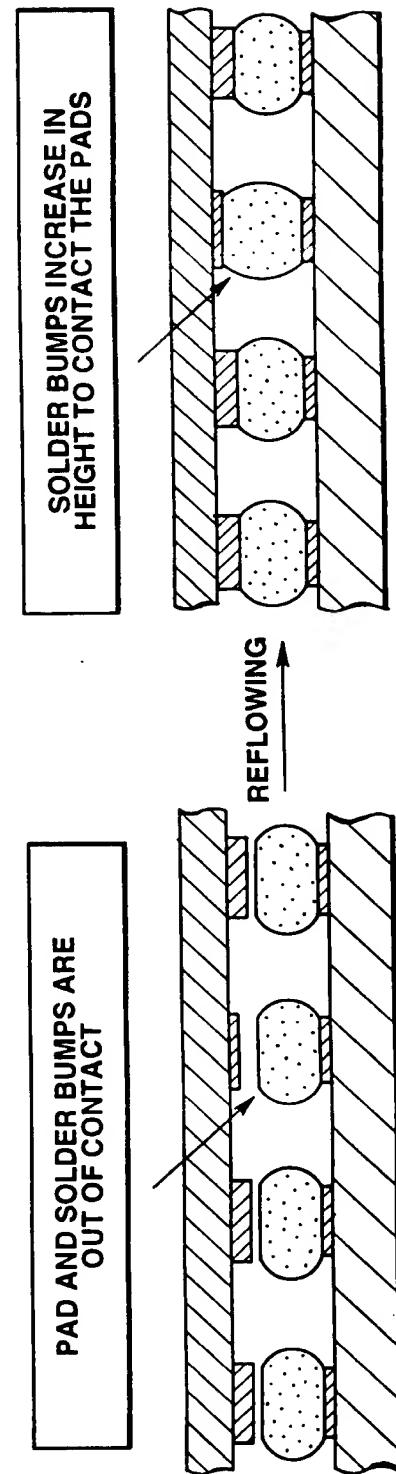
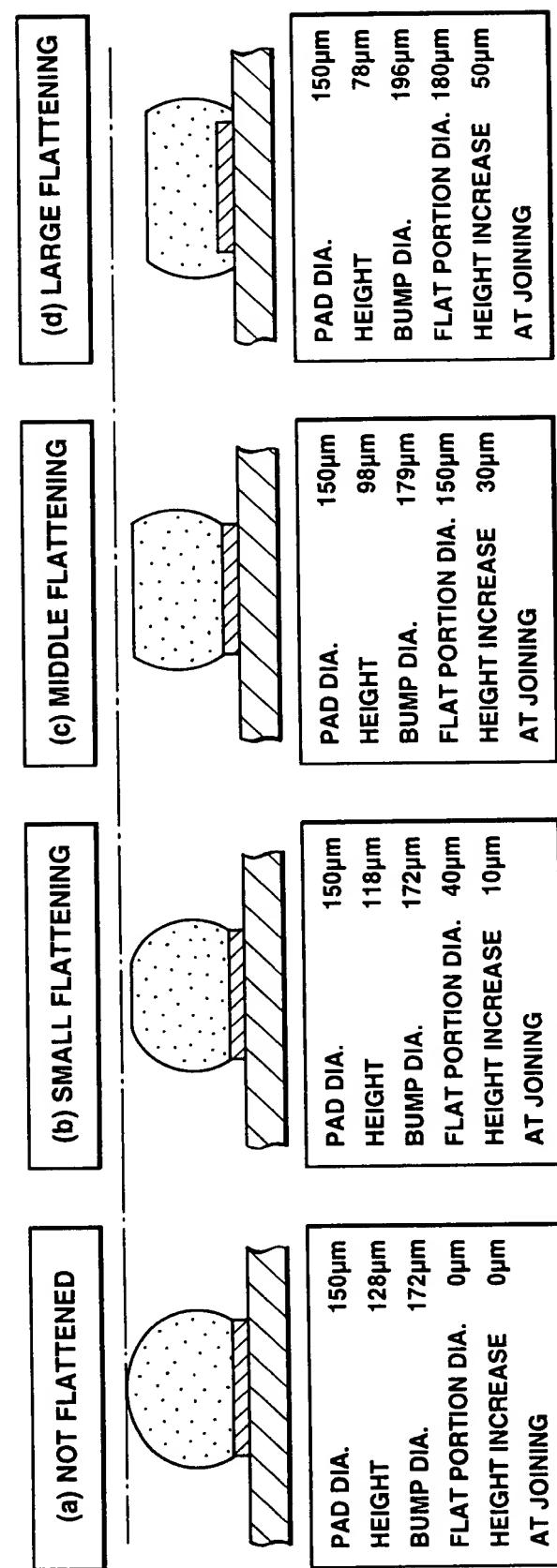


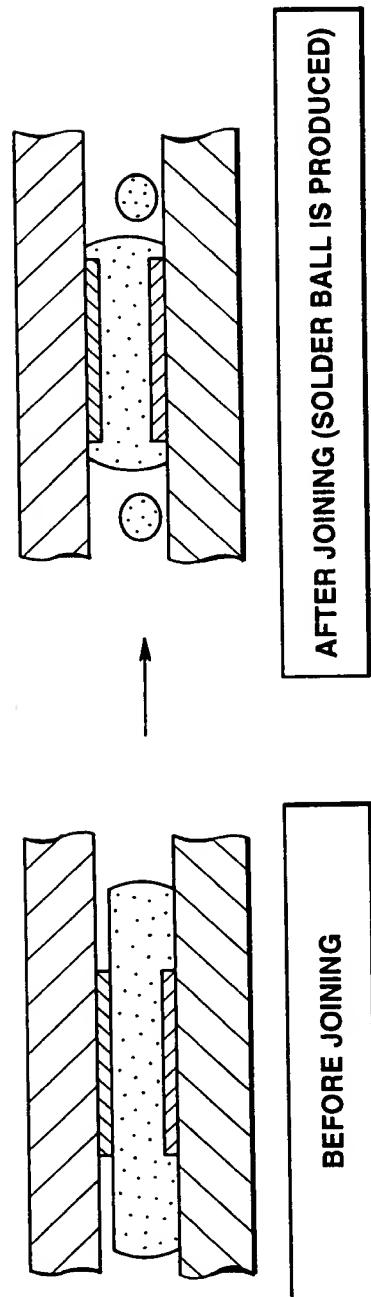
FIG.8



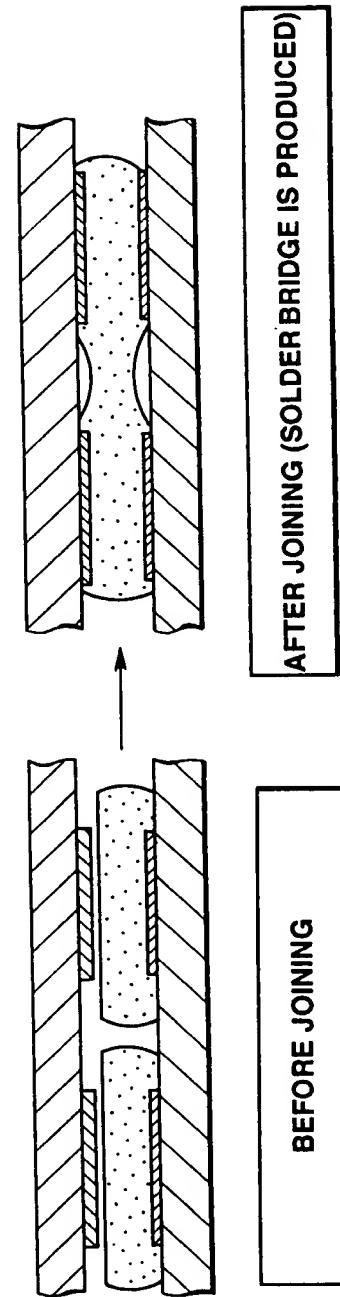


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RELATING TO CIRCUIT BOARD  
HAVING SOLDER BUMPS  
Inventor(s): Haruhiko MURATA et al.  
Appl. No.: 08/825,400

**FIG. 9**



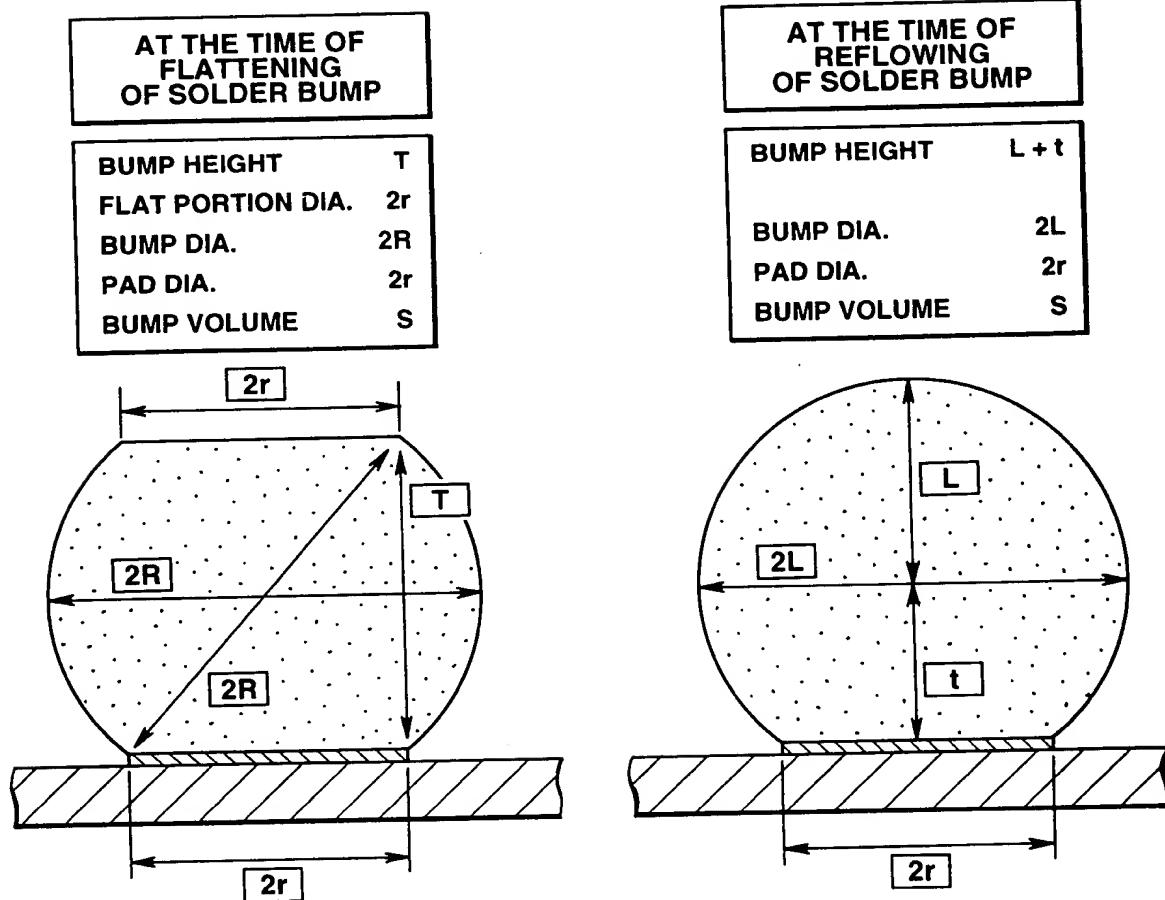
**FIG. 10**





Title: IMPROVEMENT IN OR  
RELATING TO CIRCUIT BOARD  
HAVING SOLDER BUMPS  
Inventor(s): Haruhiko MURATA et al.  
Appl. No.: 08/825,400

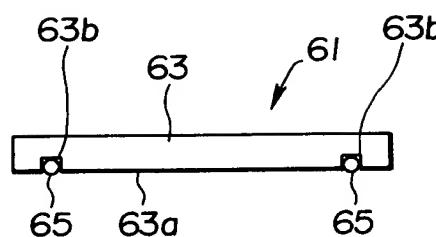
**FIG.11A**



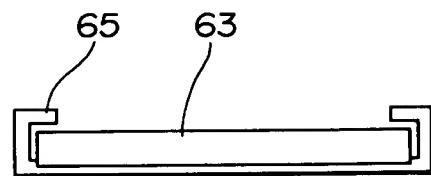
**FIG.11B**



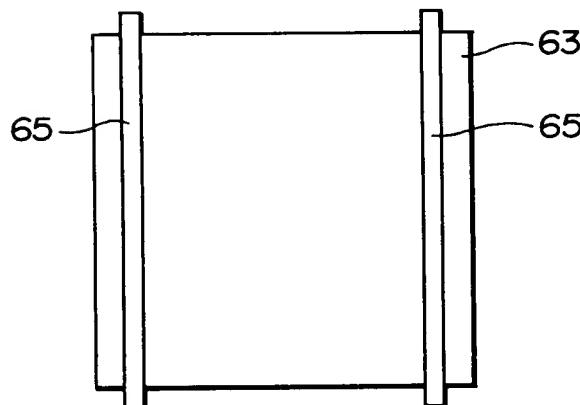
**FIG.12A**



**FIG.12C**



**FIG.12B**



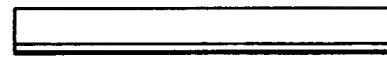


Title: IMPROVEMENT IN OR  
RELATING TO CIRCUIT BOARD  
HAVING SOLDER BUMPS  
Inventor(s): Haruhiko MURATA et al.  
Appl. No.: 08/825,400

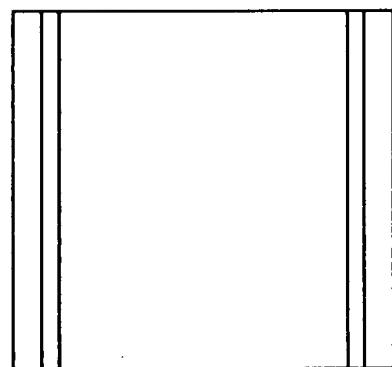
**FIG.13A**



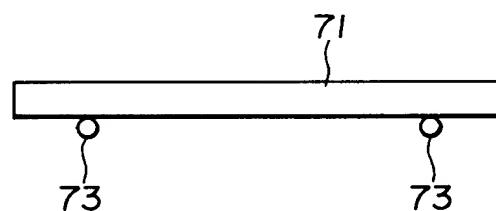
**FIG.13C**



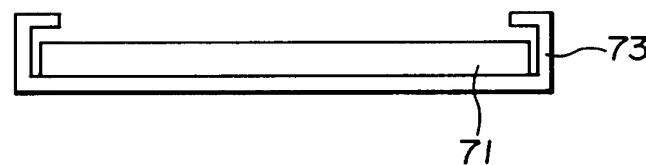
**FIG.13B**



**FIG.14A**



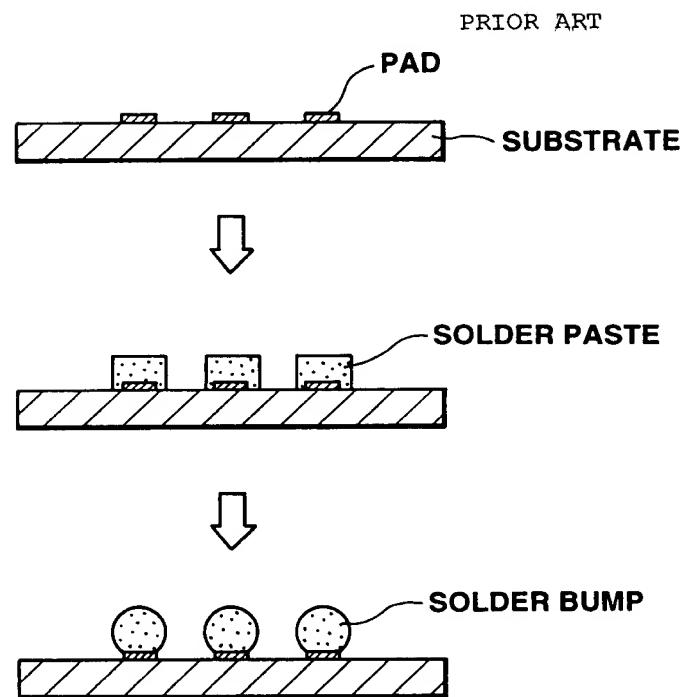
**FIG.14B**





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## FIG.15A



## FIG.15B

